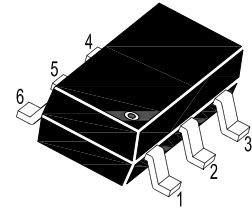
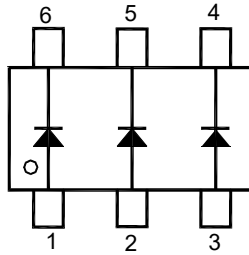


BAS16DW-AH

Silicon Epitaxial Planar Switching Diode

Features

- AEC-Q101 Qualified
- Fast switching speed
- Ultra-small surface mount package
- For general purpose switching applications
- High conductance
- Halogen and Antimony Free(HAF),
RoHS compliant



1.Anode 2. Anode 3.Anode
4. Cathode 5. Cathode 6.Cathode
SOT-363 Plastic package

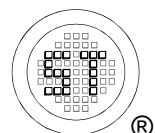
Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V_{RM}	100	V
Reverse Voltage	V_R	100	V
Average Rectified Forward Current	$I_{F(AV)}$	200	mA
Forward Continuous Current	I_{FM}	300	mA
Non-Repetitive Peak Forward Current	I_{FSM}	2 1	A
Power Dissipation	P_D	200	mW
Operating Junction and Storage Temperature Range	T_j, T_{stg}	- 65 to + 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient ¹⁾	$R_{\theta JA}$	625	$^\circ\text{C/W}$

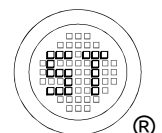
¹⁾ Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.



BAS16DW-AH

Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Min.	Max.	Unit
Reverse Breakdown Voltage at $I_R = 100 \mu\text{A}$	$V_{(BR)R}$	100	-	V
Forward Voltage at $I_F = 1 \text{ mA}$ at $I_F = 10 \text{ mA}$ at $I_F = 50 \text{ mA}$ at $I_F = 150 \text{ mA}$	V_F	- - - -	0.715 0.855 1 1.25	V
Peak Reverse Current at $V_R = 20 \text{ V}$ at $V_R = 75 \text{ V}$ at $V_R = 25 \text{ V}, T_j = 150^\circ\text{C}$ at $V_R = 75 \text{ V}, T_j = 150^\circ\text{C}$	I_R	- - - -	25 1 30 50	nA μA μA μA
Total Capacitance at $V_R = 0 \text{ V}, f = 1 \text{ MHz}$	C_T	-	2	pF
Reverse Recovery Time at $I_F = 10 \text{ mA}, V_R = 6 \text{ V}, I_{rr} = 0.1 \times I_R, R_L = 100 \Omega$	t_{rr}	-	4	ns



BAS16DW-AH

Electrical Characteristics Curves

Fig 1. Power Derating Curve

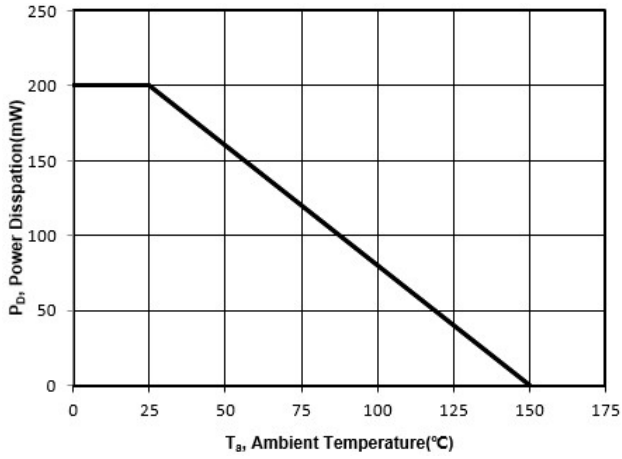


Fig 2. Total Capacitance vs. Reverse Voltage

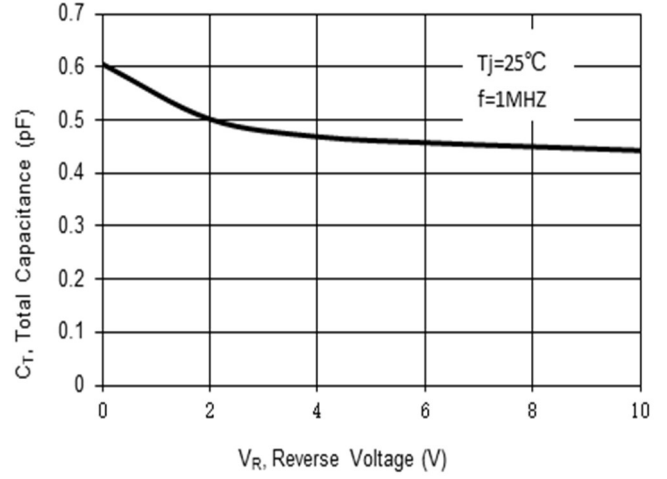


Fig 3. Reverse Current vs. Reverse Voltage

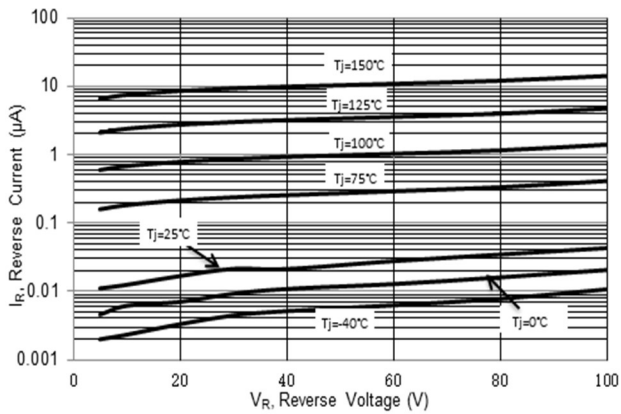
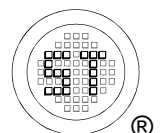
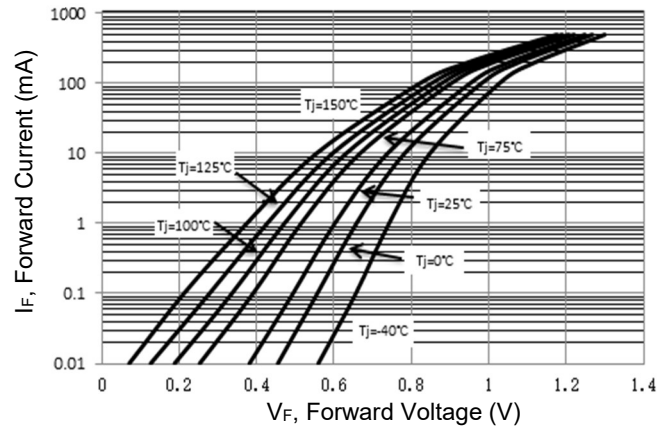


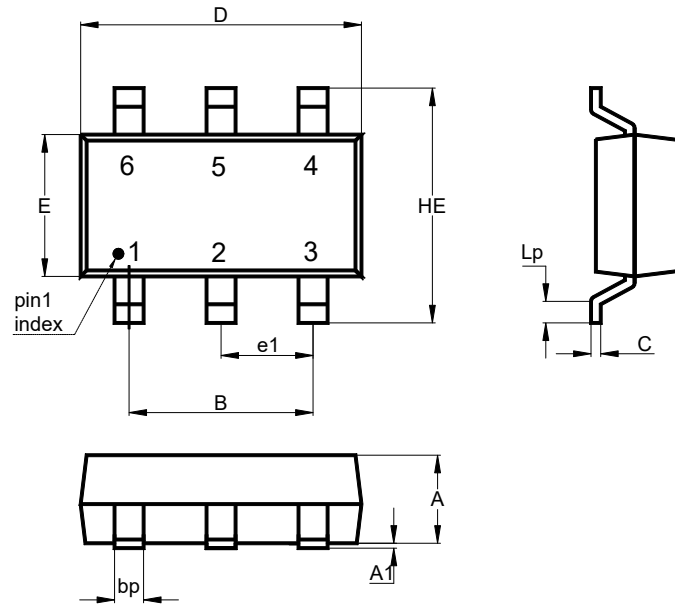
Fig 4. Forward Characteristics



BAS16DW-AH

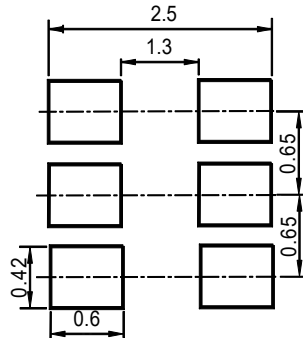
Package Outline (Dimensions in mm)

SOT-363



Unit	A	A1	B	C	D	E	e1	HE	Lp	bp
mm	1.0 0.9	0.1 0	1.3 typ.	0.25 0.1	2.2 1.8	1.35 1.15	0.65 typ.	2.2 2.0	0.4 0.15	0.3 0.1

Recommended Soldering Footprint



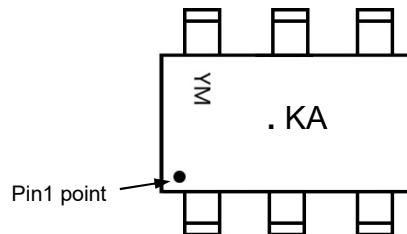
Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-363	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

- " KA " = Part No.
- " • " = HAF (Halogen and Antimony Free)
- " YM " = Date Code Marking
- " Y " = Year
- " M " = Month

Font type: Arial



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